

## General Description

This planar stripe MOSFET has better characteristics, such as fast switching time, fast reverse recovery time, low on resistance, low gate charge and excellent avalanche characteristics. It is mainly suitable for electronic ballast and switching mode power supplies.

## FEATURES

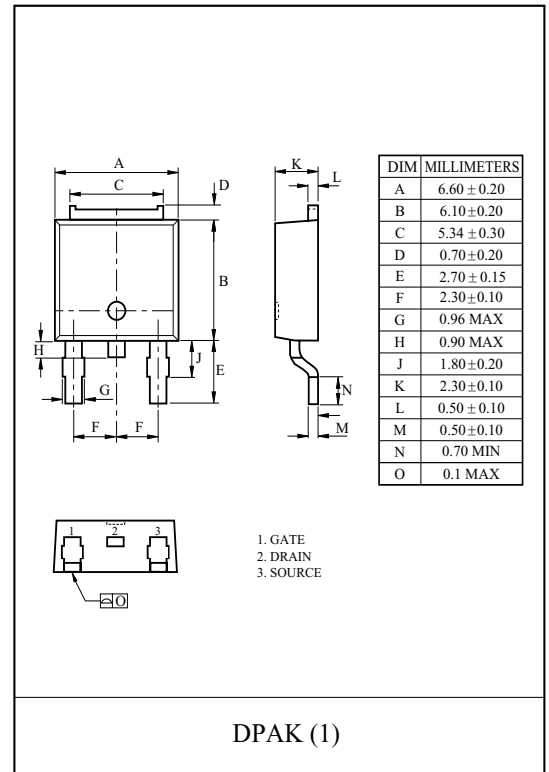
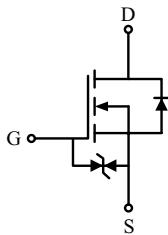
- $V_{DSS} = 500V$ ,  $I_D = 2.5A$
- Drain-Source ON Resistance :  $R_{DS(ON)} = 2.5$  (Max) @  $V_{GS} = 10V$
- $Q_g(\text{typ}) = 7.50nC$
- $t_{rr}(\text{typ}) = 120ns$  (KF3N50DS)
- $t_{rr}(\text{typ}) = 300ns$  (KF3N50DZ)

## MAXIMUM RATING (Tc=25 )

CHARACTERISTIC	SYMBOL	RATING	UNIT
Drain-Source Voltage	$V_{DSS}$	500	V
Gate-Source Voltage	$V_{GSS}$	$\pm 30$	V
Drain Current	@T <sub>C</sub> =25	2.5	A
	@T <sub>C</sub> =100	1.5	
	Pulsed (Note1)	7	
Single Pulsed Avalanche Energy (Note 2)	$E_{AS}$	110	mJ
Repetitive Avalanche Energy (Note 1)	$E_{AR}$	4	mJ
Peak Diode Recovery dv/dt (Note 3)	dv/dt	10	V/ns
Drain Power Dissipation	Tc=25	40	W
	Derate above 25	0.32	W/
Maximum Junction Temperature	T <sub>j</sub>	150	
Storage Temperature Range	T <sub>stg</sub>	-55 150	
<b>Thermal Characteristics</b>			
Thermal Resistance, Junction-to-Case	R <sub>thJC</sub>	3.1	/W
Thermal Resistance, Junction-to-Ambient	R <sub>thJA</sub>	110	/W

## PIN CONNECTION

(KF3N50DZ/DS)



# KF3N50DZ/DS

## ELECTRICAL CHARACTERISTICS (Tc=25 °C)

CHARACTERISTIC	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
<b>Static</b>						
Drain-Source Breakdown Voltage	$BV_{DSS}$	$I_D=250\mu A, V_{GS}=0V$	500	-	-	V
Breakdown Voltage Temperature Coefficient	$BV_{DSS}/T_j$	$I_D=250\mu A$ , Referenced to 25	-	0.55	-	V/°C
Drain Cut-off Current	$I_{DSS}$	$V_{DS}=500V, V_{GS}=0V$ ,	-	-	10	$\mu A$
Gate Threshold Voltage	$V_{th}$	$V_{DS}=V_{GS}, I_D=250\mu A$	2.5	-	4.5	V
Gate Leakage Current	$I_{GSS}$	$V_{GS}=\pm 25V, V_{DS}=0V$	-	-	$\pm 10$	$\mu A$
Drain-Source ON Resistance	$R_{DS(ON)}$	$V_{GS}=10V, I_D=1.25A$	-	2.0	2.5	$\Omega$
<b>Dynamic</b>						
Total Gate Charge	$Q_g$	$V_{DS}=400V, I_D=3A$ $V_{GS}=10V$ (Note4,5)	-	8.0	-	nC
Gate-Source Charge	$Q_{gs}$		-	2.0	-	
Gate-Drain Charge	$Q_{gd}$		-	3.5	-	
Turn-on Delay time	$t_{d(on)}$	$V_{DD}=250V$ $I_D=3A$ $R_G=25$ (Note4,5)	-	15	-	ns
Turn-on Rise time	$t_r$		-	20	-	
Turn-off Delay time	$t_{d(off)}$		-	25	-	
Turn-off Fall time	$t_f$		-	20	-	
Input Capacitance	$C_{iss}$	$V_{DS}=25V, V_{GS}=0V, f=1.0MHz$	-	350	-	pF
Output Capacitance	$C_{oss}$		-	45	-	
Reverse Transfer Capacitance	$C_{rss}$		-	4.5	-	
<b>Source-Drain Diode Ratings</b>						
Continuous Source Current	$I_S$	$V_{GS}<V_{th}$	-	-	3	A
Pulsed Source Current	$I_{SP}$		-	-	12	
Diode Forward Voltage	$V_{SD}$	$I_S=2.5A, V_{GS}=0V$	-	-	1.4	V
Reverse Recovery Time	KF3N50DZ	$I_S=3A, V_{GS}=0V,$ $dI_S/dt=100A/\mu s$	-	300	-	ns
	KF3N50DS		-	120	-	
Reverse Recovery Charge	KF3N50DZ		-	1.1	-	$\mu C$
	KF3N50DS		-	0.25	-	

Note 1) Repetivity rating : Pulse width limited by junction temperature.

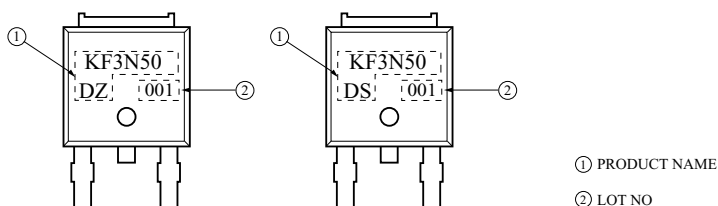
Note 2)  $L=22mH, I_S=3A, V_{DD}=50V, R_G=25$  , Starting  $T_j=25$  .

Note 3)  $I_S \leq 3A, dI/dt \leq 100A/\mu s, V_{DD} \leq BV_{DSS}$ , Starting  $T_j=25$  .

Note 4) Pulse Test : Pulse width  $\leq 300\mu s$ , Duty Cycle  $\leq 2\%$ .

Note 5) Essentially independent of operating temperature.

### Marking



# KF3N50DZ/DS

Fig1.  $I_D - V_{DS}$

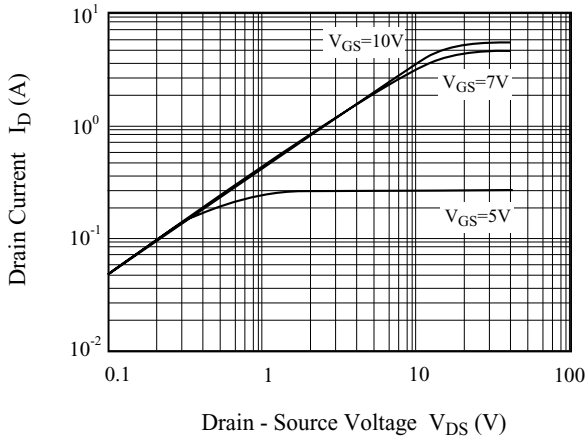


Fig2.  $I_D - V_{GS}$

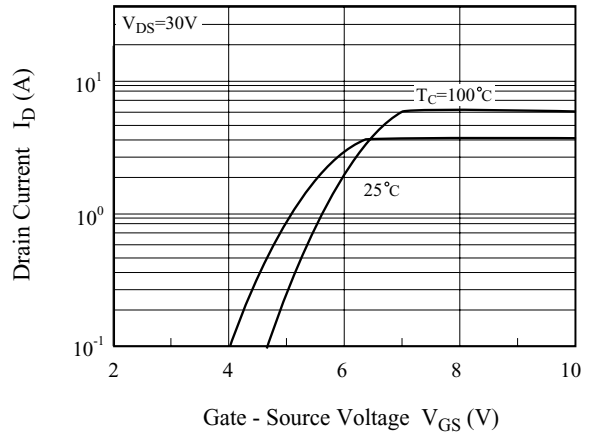


Fig3.  $BV_{DSS} - T_j$

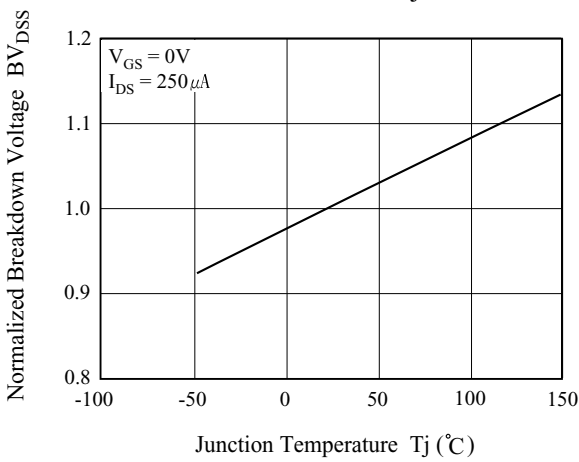


Fig4.  $R_{DS(ON)} - I_D$

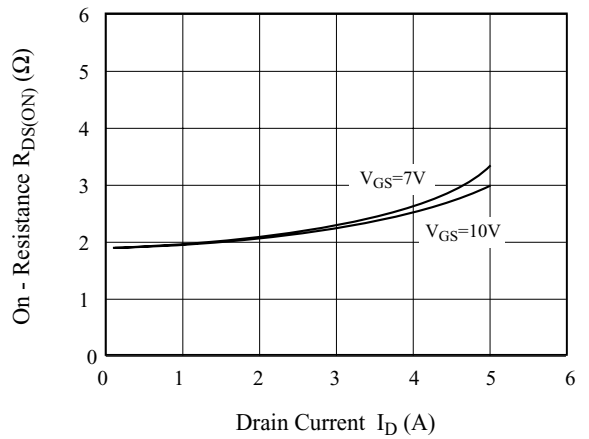


Fig5.  $I_S - V_{SD}$

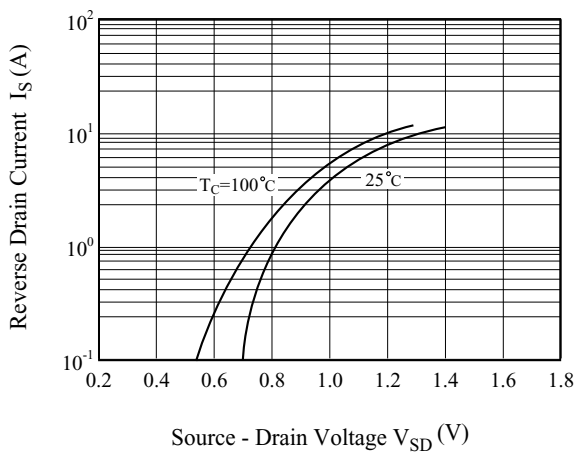
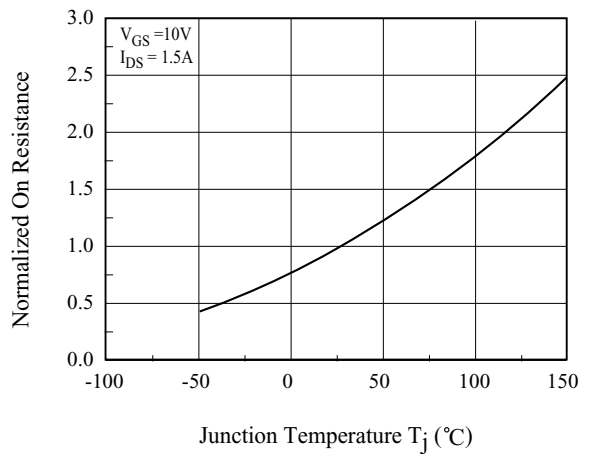


Fig6.  $R_{DS(ON)} - T_j$



# KF3N50DZ/DS

Fig 7. C - V<sub>DS</sub>

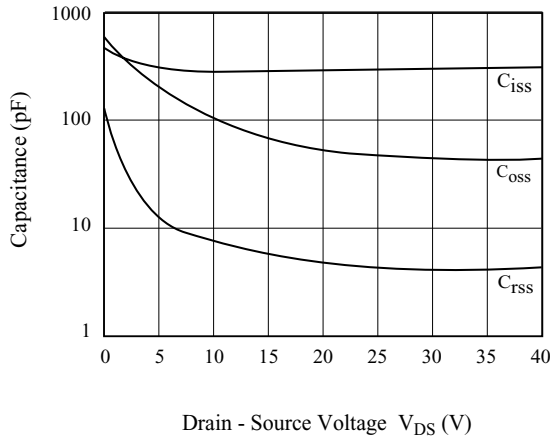


Fig8. Q<sub>g</sub>- V<sub>GS</sub>

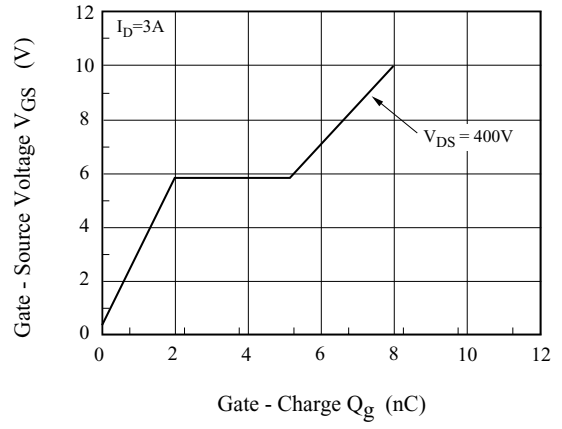


Fig9. Safe Operation Area

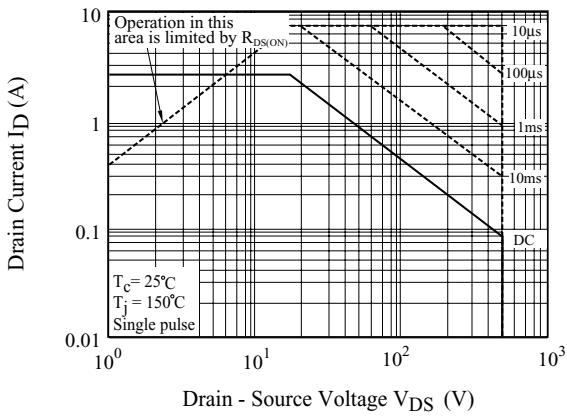


Fig10. I<sub>D</sub> - T<sub>j</sub>

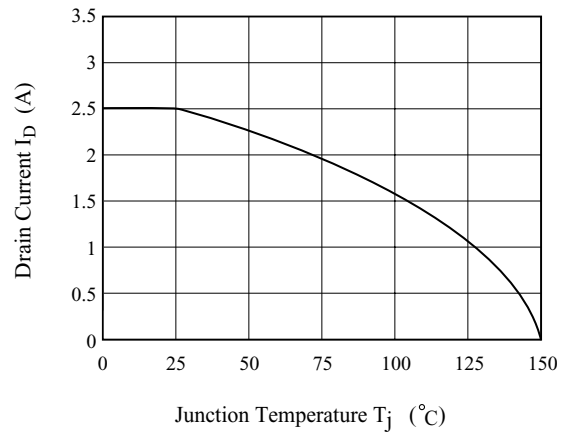


Fig11. Transient Thermal Response Curve

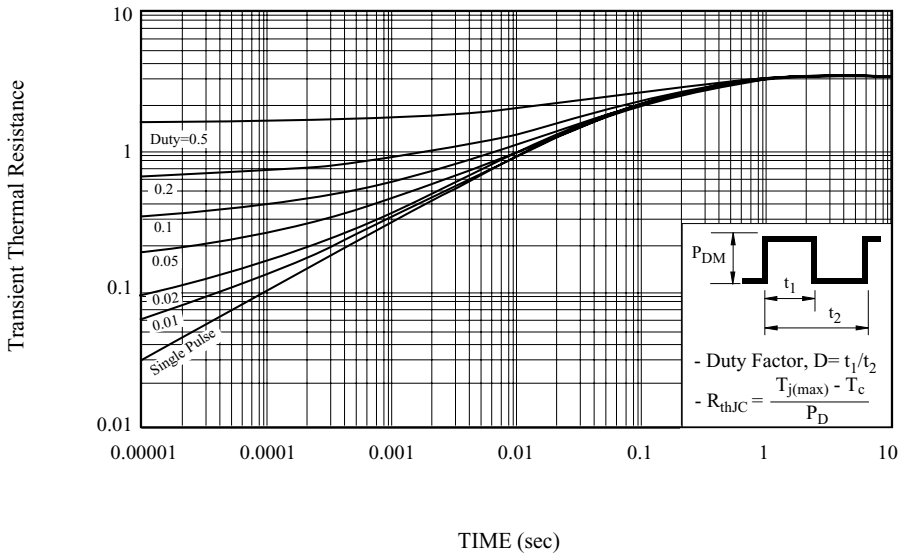


Fig12. Gate Charge

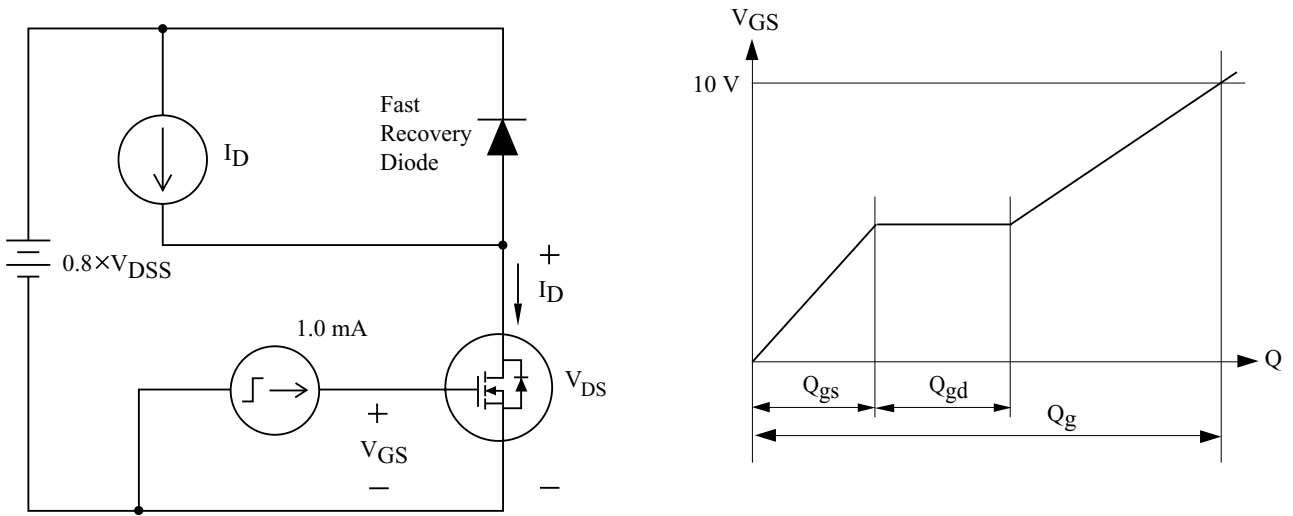


Fig13. Single Pulsed Avalanche Energy

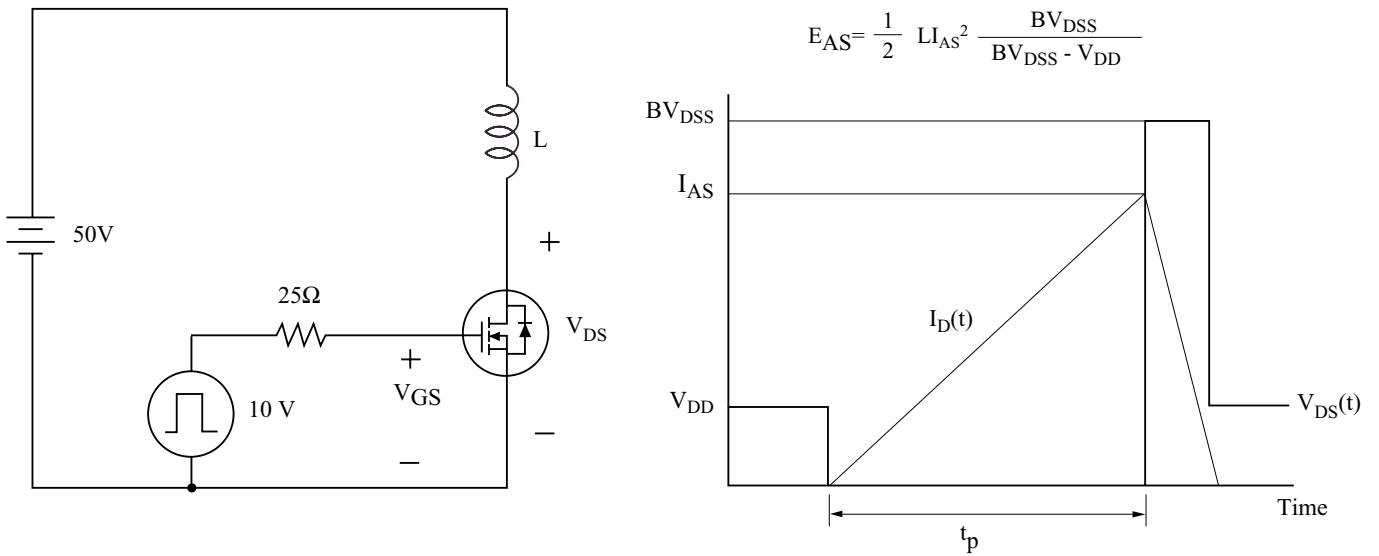


Fig14. Resistive Load Switching

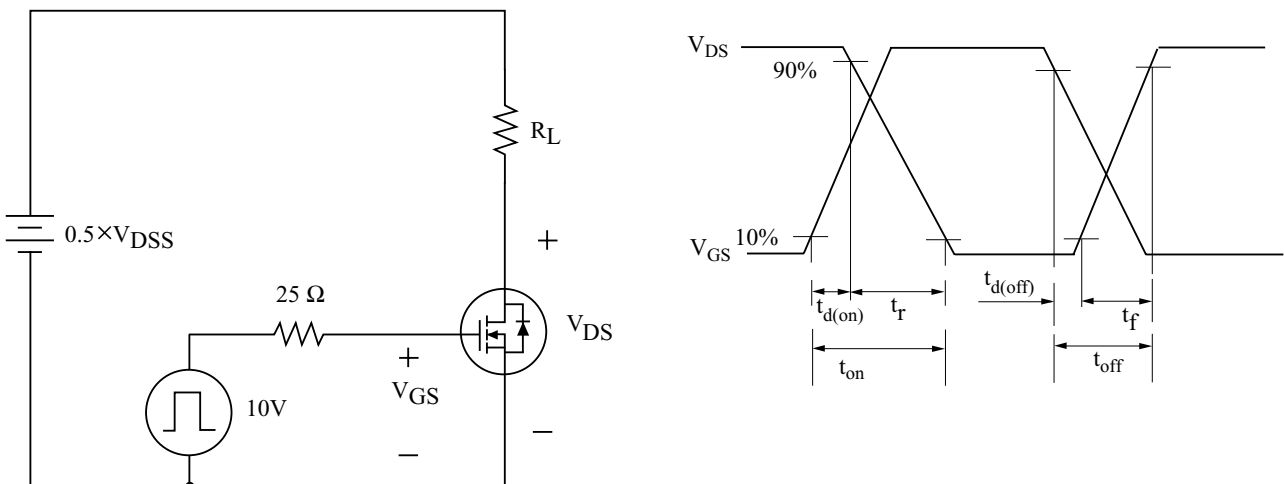


Fig15. Source - Drain Diode Reverse Recovery and  $dv/dt$

